Ultra High Performance BGA Cooling Solutions w/ maxiGRIP™ Attachment*

DIGI-KEY PART # ATS1007-ND

ATS PART # ATS-50300B-C2-R0

Features & Benefits

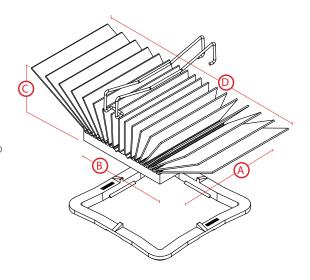
maxiFLOW™ design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling

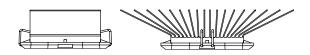
maxiGRIP™ attachment applies steady, even pressure to the component and does not require holes in the PCB

Meets Telcordia GR-63-Core Office Vibration; ETSI 300 019 Transportation Vibration; and MIL-STD-810 Shock and Unpackaged Drop Testing standards

Comes preassembled with high performance, phase changing, thermal interface material

Designed for standard height components from 3 to 4.5mm





Thermal Performance Table

AIR VELOCITY		THERMAL RESISTANCE		
FT/MIN	M/S	°C/W (UNDUCTED)	°C/W (DUCTED)	
200	1.0	7.1	5.4	
300	1.5	5.7		
400	2.0	4.9		
500	2.5	4.4		
600	3.0	4		
700	3.5	3.7		
800	4.0	3.4		

Product Details†

DIMENSION A	DIMENSION B	DIMENSION C [§]	DIMENSION D	TIM [‡]	FINISH
30	30	7.5	43.24	C1100F	BLUE-ANODIZED

For further technical information, please contact Advanced Thermal Solutions, Inc. at **1-781-769-2800** or **www.qats.com**

- * RoHS Compliant
- ‡ TIM = Thermal Interface Material
- † Dimensions are measured in millimeters
- ◆ Dimensions A & B refer to component size
- § Dimension C = the height of the heat sink shown above and does not include the height of the attachment method



